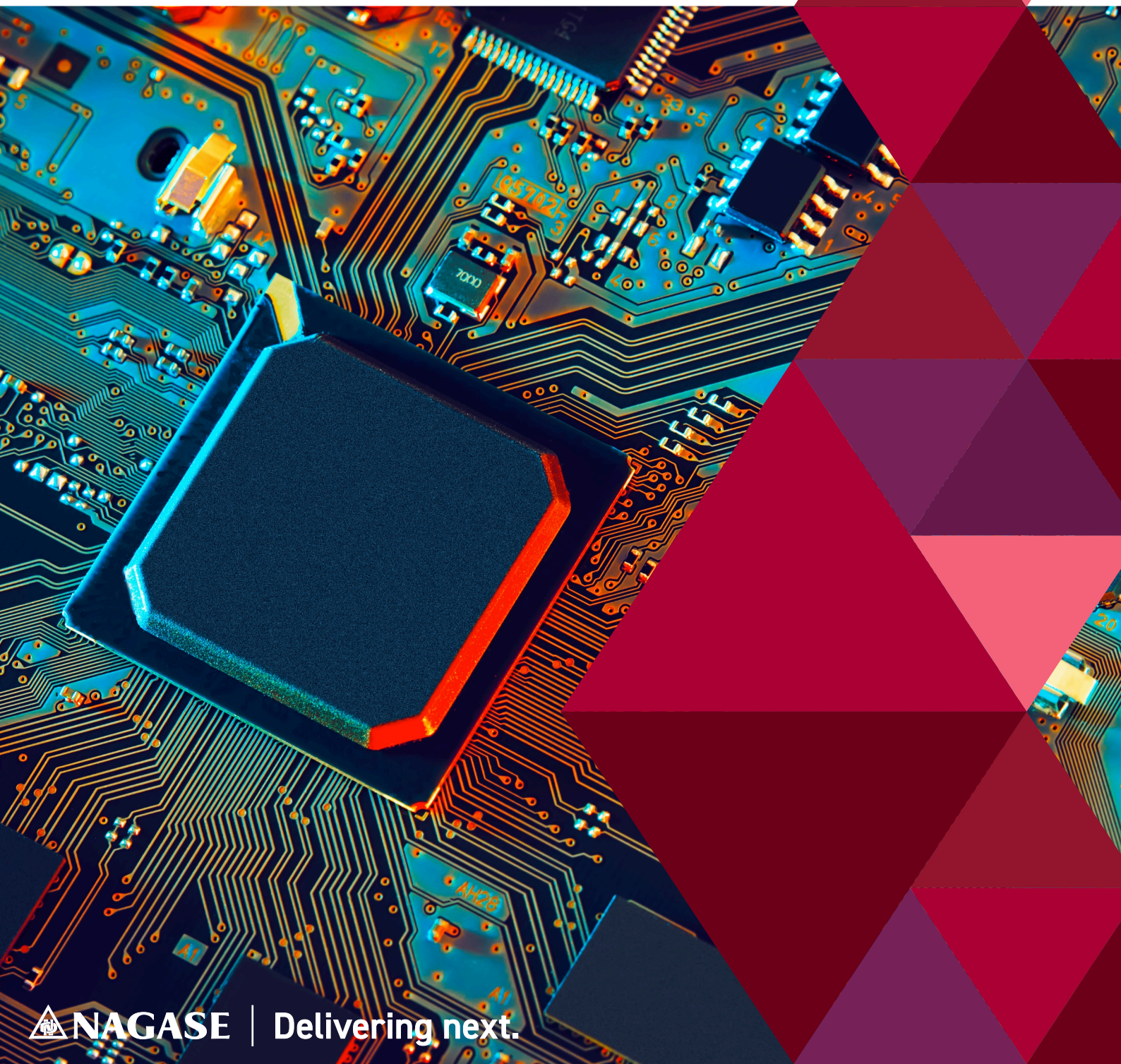
Materials for Power Devices and Electronic Components

Leading Edge Electronic Materials



NAGASE | Delivering next.

Product Lines

Printed Electronics, Microelectronics, Negative Photoresists, Photovoltaics, Automotive and Industrial

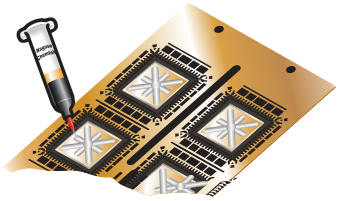
What We Do:

Our teams work to understand your requirements, recommend solutions from our product lines or, when necessary, rapidly develop custom formulations to solve application challenges.

Potting Compounds & Encapsulants

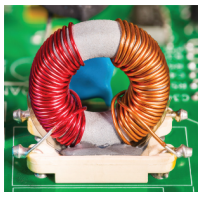
» High Thermal Conductivity
» UL 94 - Flame Retardant
» Low Coefficient of Thermal Expansion (CTE)
» High Chemical and High Temperature Resistance (Tg >150 °C)
» Applications: Power Modules, Voltage Regulators and General Pottings

Circuit Assembly Materials



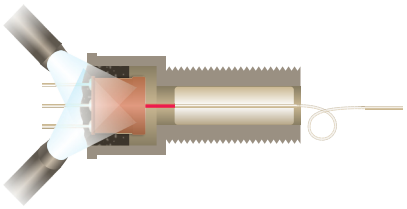
» Electrically and Thermally Conductive Adhesives
» UV or Dual Cure
» Dielectrics
» Applications: Semiconductor Packaging and Microelectronic

Low Stress Adhesives



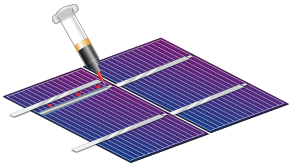
» Handle High CTE Differentials / Mismatch between Substrates
» Halogen-free Options
» Applications: Ferrite Cores Attach, Common Mode Chokes, Toroidal Transformers

Dual Cure Adhesives



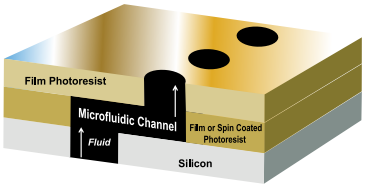
» Active Alignment
» Component Attach
» Stress Relief
» Applications: Transceivers, Lidar and Lasers

Solar Electrically Conductive Adhesives



» Shingling and Stringing
» Back Contact
» Applications: Low Ag, Perovskite Compatible and Snap Cure

Negative Tone Photoresist (Liquids & Films)



» Exceptional Resolution
» Hydrophobic - Chemically Resistant
» Available Thickness from 5 - 90 µm (up to 150 µm Stackable)
» Tough, Lower Stress than Conventional Negative Image Resists

Permanent Magnet Adhesives

» A Excellent Adhesion to Metals, Ceramics, Ni-Cu-Ni Coated Magnets, Neodymium Magnets
» Applications: Permanent Magnet Motors, Structural Bonding

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